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RoHS

COMPLIANT

TPC8118-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.011 at V _{GS} = - 10 V	- 13.5	29.5 nC		
- 30	0.015 at V_{GS} = - 4.5 V	- 11.6	29.0110		

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5 D

SO-8

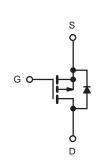
Top View

FEATURES

- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	$A = 25 \ ^{\circ}C$, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage	V _{GS}	± 20	v	
	T _C = 25 °C		- 13.5	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 11.9	
Continuous Drain Current $(T_j = 150^{\circ} C)$	T _A = 25 °C	I _D	- 10.9 ^{a, b}	
	T _A = 70 °C		- 8.6 ^{a, b}	•
Pulsed Drain Current	I _{DM}	- 50	Α	
	T _C = 25 °C	1	- 4.1	
Continuous Source-Drain Diode Current	T _A = 25 °C	Is –	- 2.2 ^{a, b}	
Avalanche Current	1 0.4 ml l	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ
	T _C = 25 °C		5.0	
Maximum Davian Disaination	T _C = 70 °C	Б	3.2	14/
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	W
	T _A = 70 °C	1	1.7 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	0,00	

Notes:

b. t = 10 s.

c. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

d. Based on T_C = 25 °C.

a. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	• • • • • • • • • • • • • • • • • • • •			.,,,,,			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J			- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μΑ		5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 1.4		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 100	nA	
5		$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			Α	
	_	V _{GS} = - 10 V, I _D = - 10 A		0.011		- Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 8 A		0.015			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b				11		1	
Input Capacitance	C _{iss}			2550			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		455		pF	
Reverse Transfer Capacitance	C _{rss}			390			
		V_{DS} = - 15 V, V_{GS} = - 10 V, I_{D} = - 10 A		57	86	86	
Total Gate Charge	Q_g		29.5	45			
Gate-Source Charge	Q _{gs}	V_{DS} = - 15 V, V_{GS} = - 4.5 V, I_{D} = - 10 A		8		nC	
Gate-Drain Charge	Q _{gd}			22			
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		12	24		
Turn-Off DelayTime	t _{d(off)}	${\rm I}_{\rm D}\cong$ - 10 A, ${\rm V}_{\rm GEN}$ = - 10 V, ${\rm R}_{\rm g}$ = 1 Ω		40	70		
Fall Time	t _f			9	18		
Turn-On Delay Time	t _{d(on)}			48	80	ns	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 1.5 Ω		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		34	60		
Fall Time	t _f			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.1	А	
Pulse Diode Forward Current	I _{SM}				- 60	А	
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 10 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		16	27	nC	
Reverse Recovery Fall Time	t _a	$r_{\rm F} = -10$ A, u/u = 100 A/µs, $r_{\rm J} = 25$ °C		12			
Reverse Recovery Rise Time	t _b	1		15		ns	

Notes:

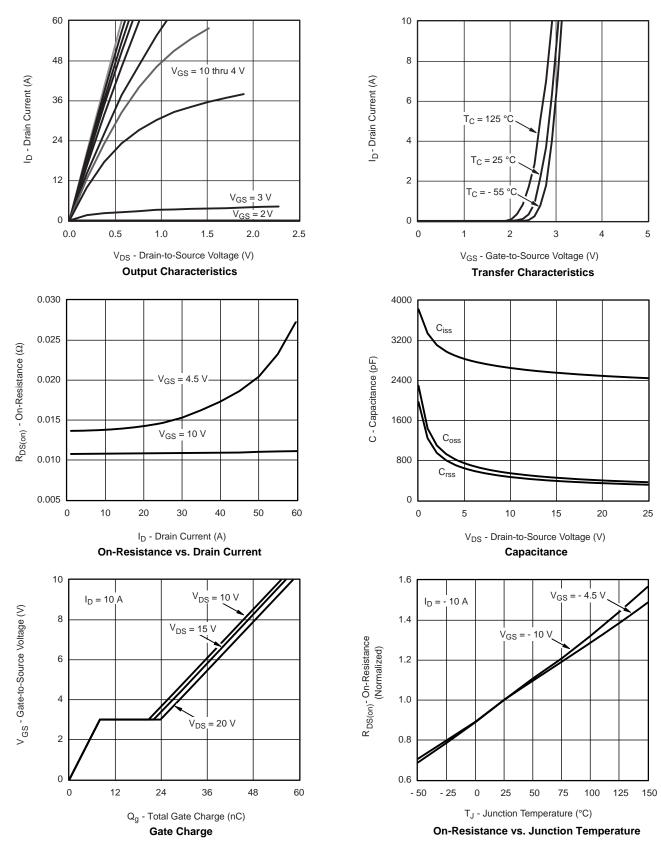
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.









I_D = 10 A

T_J = 25 °C

10

10

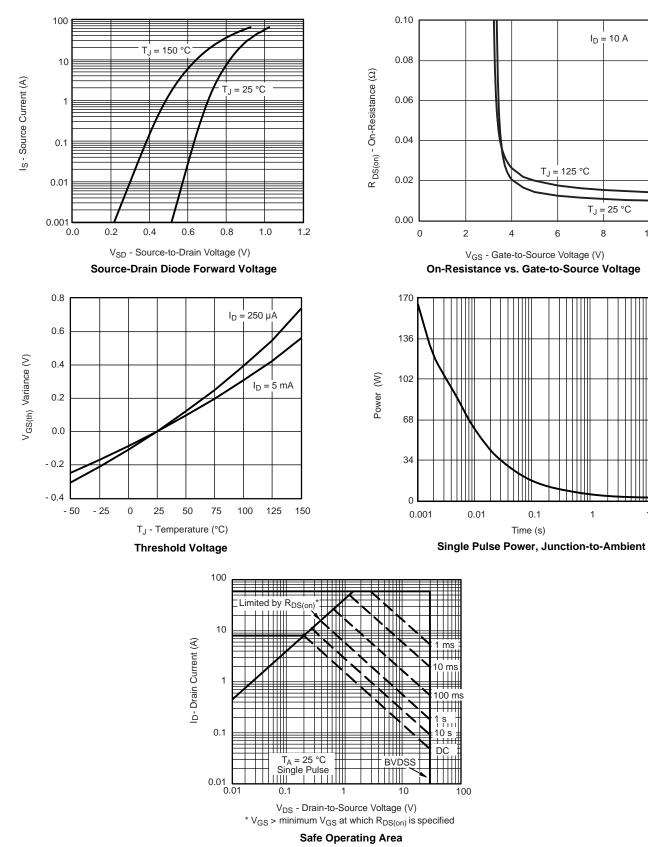
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T_J = 125 °C

6

0.1

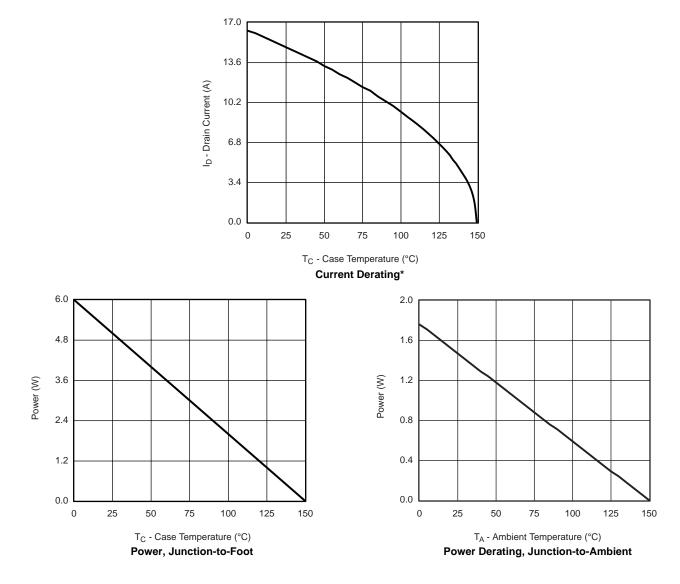
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



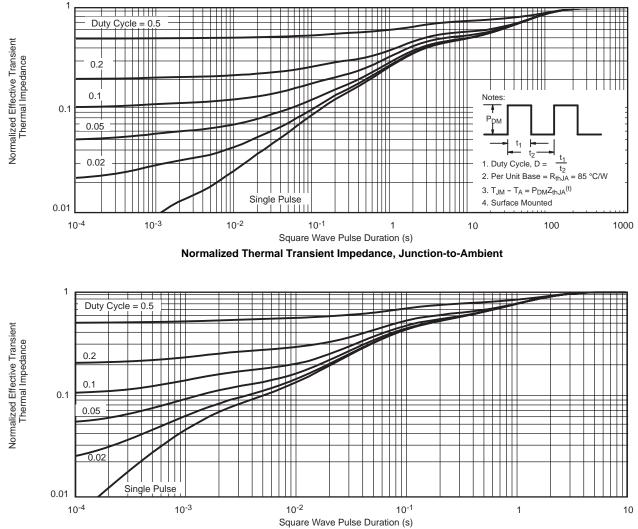
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.







Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012





	MILLIM	ETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050	0.050 BSC		
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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